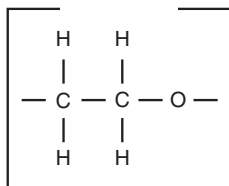


## G16 phase

### Stabilwax® Structure



### similar phases

DB-WAX, DB-WAXetr, HP-Wax, HP-Innowax, Supelcowax 10, CP-Wax 52 CB

## Organic Volatile Impurities (OVI) Analysis

### Stabilwax® Columns (fused silica)

(polar phase; Crossbond® Carbowax® polyethylene glycol)

- Most stable polyethylene glycol (PEG) column available.
- Rugged enough to withstand repeated water injections.
- Lowest bleed PEG column on the market; long column lifetimes are assured
- Temperature range: 40 °C to 260 °C.
- Equivalent to USP G14, G15, G16, G20, and G39 phases.

Restek's polar-deactivated surface tightly binds the Carbowax® polymer and increases thermal stability, relative to competitive columns. Because of the increased stability produced by the bonding process, Stabilwax® columns exhibit long column lifetimes, even when programming repeatedly up to 260 °C. The bonding mechanism of the column also produces polar compound retention times that do not shift as is often observed on other wax-type columns. In addition, this bonding mechanism produces a column that can be rejuvenated by solvent washing.

ID	df	temp. limits	30-Meter
0.32mm	0.25µm	40 to 250/260°C	10624
0.53mm	0.25µm	40 to 250/260°C	10625

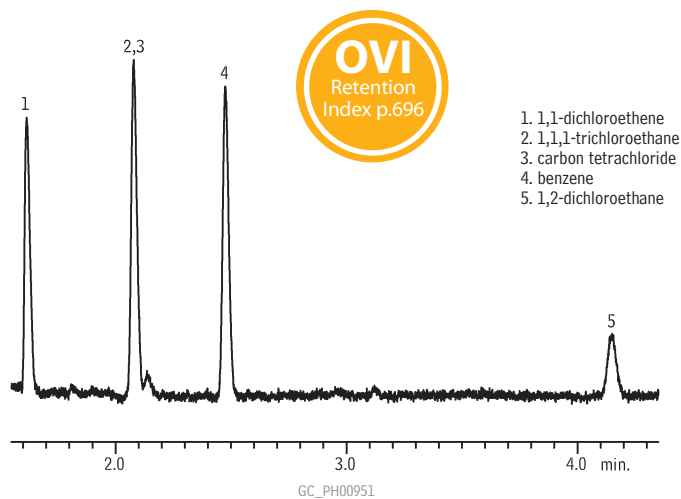
For our complete listing of Stabilwax® columns, see **page 59**.

### ordering note

#### Get the protection without the connection!

For Stabilwax® columns with built-in Integra-Guard® guard columns, see **page 35**.

### Class 1 residual solvents on a Stabilwax® (G16) column.



- 1,1-dichloroethene
- 1,1,1-trichloroethane
- carbon tetrachloride
- benzene
- 1,2-dichloroethane



### free literature

#### Residual Solvent Analysis

Download your free copy from [www.restek.com](http://www.restek.com)  
lit. cat.# PHFL1018A

Column: Stabilwax®, 30m, 0.32mm ID, 0.25µm (cat.# 10624)  
Sample: USP Stock Mixture USP <467> Residual Solvents Class 1 Mix (cat.# 36279) in 20mL headspace vial (cat.# 24685), water diluent  
Inj.: headspace injection (split ratio 1:5), 2mm splitless liner IP deactivated (cat.# 20712)  
Inj. temp.: 140°C  
Carrier gas: helium, constant flow  
Flow rate: 2.15mL/min., 35.2cm/sec.  
Oven temp.: 50°C for 20 min. to 165°C @ 6°C/min. (hold for 20 min.)  
Det.: FID @ 250°C

Headspace Conditions  
Instrument: Overbrook Scientific HT200H  
Syringe temp.: 100°C  
Sample temp.: 80°C  
Sample equil. time.: 45 min.  
Injection vol.: 1.0mL  
Injection speed: setting 8  
Injection dwell: 5 sec.